HEWLETT-PACKARD COMPANY
Intellectual Property Administration
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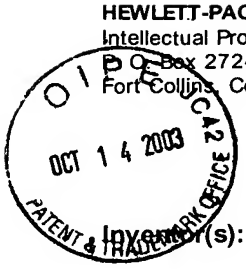
Fort Collins, Colorado 80527-2400



PATENT APPLICATION

ATTORNEY DOCKET NO. 100203431-1

IN THE
UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s): Bash et al.

Confirmation No.:

Application No.: 10/664,256

Examiner:

Filing Date: Sept. 17, 2003

Group Art Unit:

Title: Dynamic Fluid Sprayjet Delivery System

Commissioner for Patents
PO Box 1450
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:

This Information Disclosure Statement is submitted:

(X) under 37 CFR 1.97(b), or
(Within three months of filing national application; or date of entry of national application; or before mailing date of first office action on the merits; whichever occurs last)

( ) under 37 CFR 1.97 (c) together with either a:
( ) Statement under 37 CFR 1.97(e), or
( ) a $180.00 fee under 37 CFR 1.17(p), or
(After the CFR 1.97 (b) time period, but before final action or notice of allowance, whichever occurs first)

( ) under 37 CFR 1.97 (d) together with a:
( ) Statement under 37 CFR 1.97(e)(1) or (2), and
( ) a $180.00 fee set forth in 37 CFR 1.17(p).
(Filed after final action, a notice of allowance, on or before payment of the issue fee)

Please charge to Deposit Account **08-2025** the sum of $0.00 . At any time during the pendency of this application, please charge any fees required or credit any overpayment to Deposit Account **08-2025** pursuant to 37 CFR 1.25.

(X) Applicant(s) submit herewith Form PTO 1449 - Information Disclosure Statement together with any required copies of patents, publications or other information of which applicant(s) are aware, which applicant(s) believe(s) may be material to the examination of this application and for which there may be a duty to disclose in accordance with 37 CFR 1.56.

( ) A concise explanation of the relevance of foreign language patents, foreign language publications and other foreign language information listed on PTO Form 1449, as presently understood by the individuals(s) designated in 37 CFR 1.56 (c) most knowledgeable about the content is given on the attached sheet, or where a foreign language patent is cited in a search report or other action by a foreign patent office in a counterpart foreign application, an English language version of the search report or action which indicates the degree of relevance found by the foreign office is listed on form PTO 1449 and is enclosed herewith.

It is requested that the information disclosed herein be made of record in this application.

(X) I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313-1450. Date of Deposit: October 9, 2003

OR

( ) I hereby certify that this paper is being transmitted to the Patent and Trademark Office facsimile number_____ on _____
Number of pages:

Typed Name: John Griecci

Signature: _____

Rev 10/03 (IDSCERT)

Respectfully submitted,

Bash et al.

By _____

John Griecci

Attorney/Agent for Applicant(s)
Reg. No. **39,694**

Date: **Oct. 9, 2003**

Telephone No.: **(310) 376-6527**

Application No.	:	10/664,256	Confirmation No. _____
Applicant	:	BASH et al.	
Filed	:	September 17, 2003	
Art Unit	:		
Examiner	:		
Docket No.	:	100203431-1	
Customer No.	:	22879	
Date:	:	October 9, 2003	

Honorable Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

DISCLOSURE OF PENDING APPLICATIONS

Dear Sir:

With respect to the above-identified application, Applicants respectfully note that the following patent applications include claims directed to related technologies:

U.S. Patent Application, Serial No. 09/945,044, filed August 31, 2001;
U.S. Patent Application, Serial No. 10/023,227, filed December 14, 2001; and
U.S. Patent Application, Serial No. 10/384,456, filed March 7, 2003.

The filing of this disclosure should not be construed to be either a suggestion or an admission that the cited applications are, or are considered to be, material to patentability under 37 C.F.R. § 1.56(b).

Respectfully submitted,

Bash et al.

By: _____
John A. Griecci
Registration No. 39,694
For: The Law Office of John A. Griecci

703 Pier Avenue, Suite B #657
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PATENT APPLICATION

FORM PTO-1449

LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT

(Use several sheets if necessary)

ATTY. DOCKET NO.	SERIAL NO.
100203431-1	10/664,256
APPLICANT: BASH et al.	
FILING DATE: September 17, 2003	GROUP

REFERENCE DESIGNATION **U.S. PATENT DOCUMENTS**

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS
		6,205,799 B1	Mar. 27, 2001	Patel et al.	62	132
		6,182,742 B1	Feb. 6, 2001	Takahashi et al.	165	104.33
		6,108,201	Aug. 22, 2000	Tilton et al.	361	689
		5,943,211	Aug. 24, 1999	Havey et al.	361	699
		5,924,198	Jul. 20, 1999	Swanson et al.	29	890.1
		5,907,473	May 25, 1999	Przilas et al.	361	699
		5,724,824	Mar. 10 1998	Parsons	62	171
		5,718,117	Feb. 17, 1998	McDunn et al.	62	64
		5,434,606	Jul. 18, 1995	Hindagolla et al.	347	45
		5,278,584	Jan. 11, 1994	Keefe et al.	346	140 R
		5,220,804	Jun. 22, 1993	Tilton et al.	62	64

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		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	TRANSLATION YES	TRANSLATION NO

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)

		Sehmbey, M.S., Pais, M.R. and Chow, L.C., "Effect of Surface Material Properties and Surface Characteristics in Evaporative Spray Cooling," THE JOURNAL OF THERMOPHYSICS & HEAT TRANSFER, July-September, 1992, Vol. 6, No. 3, pp 505-511.
		Pais, Martin R., Chang, Ming J., Morgan, Michael J. and Chow, Louis C., "Spray Cooling of a High Power Laser Diode, SAE AEROSPACE ATLANTA CONFERENCE & EXPOSITION, DAYTON, OHIO, 1994, pp 1-6.
		Morgan, Michael J., Chang, Won S., Pais, Martin R. and Chow, Louis C., "Comparison of High Heat-Flux Cooling Applications," SPIE, 1992, Vol. 1739, pp17-28

EXAMINER	DATE CONSIDERED

Rev 10/00 (PTO1449)

FORM PTO-1449 LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT (Use several sheets if necessary)	ATTY. DOCKET NO. 100203431-1	SERIAL NO. 10/664,256
	APPLICANT BASH et al.	
	FILING DATE September 17, 2003	GROUP

REFERENCE DESIGNATION **U.S. PATENT DOCUMENTS**

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS
		4,794,410	Dec. 27, 1988	Taub et al.	346	140 R
		4,685,308	Aug. 11, 1987	Welker et al.	62	171
		4,683,481	Jul. 28 1987	Johnson	346	140 R
		4,576,012	Mar. 18, 1986	Luzenberg	62	157
		4,559,789	Dec. 24, 1985	Riek	62	157
		4,500,895	Feb. 19, 1985	Buck et al.	346	140 R
		4,490,728	Dec 25, 1984	Vaught et al.	346	1.1
		4,352,392	Oct. 5, 1982	Eastman	165	104.25
		4,290,274	Sep. 22, 1981	Essex	62	157
		4,141,224	Feb. 27, 1979	Alger et al.	62	514 R
		2,875,263	Feb. 24, 1959	Narbut	174	15

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		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	TRANSLATION YES	TRANSLATION NO

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)

		Lee, Chin C., and Chien, David H., "Thermal and Package Design of High Power Laser Diodes," IEEE, 1993, Ninth IEEE Semi-Therm Symposium, pp 75-80.
		Sehmbey, Mainder S., Chow, Louis C., Pais, Martin R. and Mahefkey, Tom, "High Heat Flux Spray Cooling of Electronics," AMERICAN INSTITUTE OF PHYSICS, January, 1995, pp 903-909.
		Mudawar, I. and Estes, K.A., "Optimizing and Predicting CHF in Spray Cooling of a Square Surface," JOURNAL OF HEAT TRANSFER, August, 1996, Vol. 118, pp 672-679.

EXAMINER	DATE CONSIDERED

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LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT

(Use several sheets if necessary)

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100203431-1	10/664,256
APPLICANT: BASH et al.	
FILING DATE: September 17, 2003	GROUP:

REFERENCE DESIGNATION **U.S. PATENT DOCUMENTS**

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS
		2,858,355	Oct. 28, 1958	Narbut	174	15
		2,849,523	Aug. 26, 1958	Narbut	174	15
		2,643,282	June 23, 1953	Greene	174	15
		5,992,159	Nov. 30, 1999	Edwards et al.	62	64
		5,797,274	Aug. 25, 1998	Jackaman et al.	62	171
		5,247,426	Sep. 21, 1993	Hamburgen et al.	361	705
		5,212,975	May 25, 1993	Ginzburg	72	43

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		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	TRANSLATION YES	TRANSLATION NO

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)

		Denney, D. Lawrence, "High Heat Flux Cooling Via a Monodisperse Controllable Spray", A Thesis Presented to The Academic Faculty of Georgia Institute of Technology in Partial Fulfillment of the Requirements for the Degree Master of Science in Mechanical Engineering, March 1996.

EXAMINER	DATE CONSIDERED

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EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS
		6,393,853 B1	May 28, 2002	Vukovic et al.	62	259.2
		6,349,035 B1	Feb. 19, 2002	Koenen	361	719
		6,205,023 B1	Mar. 20, 2001	Moribe et al.	361	704
		5,640,302	June 17, 1997	Kikinis	361	687
		5,473,506	Dec. 5, 1995	Kikinis	361	688
		4,825,337	Apr. 25, 1989	Karpman	361	386
		5,658,387	Aug. 19, 1997	Reardon et al.	118	323
		6,595,014 B2	Jul. 22, 2003	Malone et al.	62	171
		6,604,370 B2	Aug. 12, 2003	Bash et al.	62	171
		6,612,120 B2	Sep. 2, 2003	Patel et al.	62	171
		6,484,521 B2	Nov. 26, 2002	Patel et al.	62	171

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		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	TRANSLATION YES	TRANSLATION NO
		EP 509844 A1	10/1992	Yamamoto et al.	165	104.33		
		JP 56-137086	10/1981	Mikane et al.	165	104.33		X

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)

		R. Hannemann, L. R. Fox and M. Mahalingham, "Thermal Design for Microelectronic Components," in "Advances in Cooling Techniques for Computers" 245-276 (Win Aung ed., Hemisphere Publishing Corporation, 1991).
		"Advances in Cooling Techniques for Computers" 150-153 (Win Aung ed., Hemisphere Publishing Corporation, 1991).
		Robert Darveaux and Iwona Turlik, "Backside Cooling of Flip Chip Devices in Multichip Modules," ICMCM Proc. 230-241 (1992).

EXAMINER	DATE CONSIDERED

Rev 10/00 (PTO1449)

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FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	TRANSLATION YES	TRANSLATION NO

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)

		Herman W. Chu, Christian L. Belady and Chandrakant D. Patel, "A Survey of High-performance, High Aspect Ratio, Air Cooled Heat Sinks," International Systems and Packaging Symposium (1999).
		Chandrakant D. Patel, "Backside Cooling Solution for High Power Flip Chip Multi-Chip Modules," IEEE ECTC Proceedings 442-449 (May, 1994).

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